

## AMENDMENTS TO THE CLAIMS

- 1 (currently amended)** A substrate processing apparatus comprising:
- a-substrate holding ~~mechanisms~~mechanism for holding a substrate, each of said substrate holding mechanisms including
    - (i) a body having a projection for supporting the substrate, and
    - (ii) a rotatable pawl having a presser configured to press the substrate from above  
with~~under~~ a holding force which is ~~produced~~ due to a centrifugal force caused by rotation of said substrate holding mechanism;
  - a substrate rotation mechanism for rotating said substrate holding ~~mechanisms~~mechanism, thereby rotating said substrate, and~~mechanism to rotate the substrate held by said substrate holding mechanism; a driving device for changing a rotational speed of said substrate holding mechanisms, thereby changing~~mechanism so as to change the holding force under which the substrate is held by said substrate holding mechanism, said substrate rotation mechanism being configured to increase or decrease a rotational speed of said substrate holding mechanisms so as to cause rotational slipping of the substrate relative to said substrate holding mechanisms; and
  - a treatment liquid supply mechanism for supplying a treatment liquid to a desired portion of the substrate held by said substrate holding ~~mechanisms~~mechanism.

**2 (canceled)**

- 3 (currently amended)** A substrate processing apparatus comprising:
- a substrate holding mechanism for holding a peripheral portion of a substrate;
  - a base member having said substrate holding mechanism attached thereto, said base member facing at least one surface of the substrate;
  - a rotatable shaft attached to a central portion of said base member;

a first liquid supply nozzle for selectively supplying a chemical liquid or a first cleaning liquid to the substrate from a first line;

a switching device for switching the chemical liquid and the first cleaning liquid to be supplied to said first nozzle;

a second liquid supply nozzle for supplying a second cleaning liquid to an inner surface of said substrate holding mechanism and an upper surface of said base member from a second line;

a gas supply nozzle for supplying a gas to a space between the substrate and said base member;

a nozzle structure including said first liquid supply nozzle, and said second liquid supply nozzle, ~~and said gas supply nozzle~~, said nozzle structure being disposed within said rotatable shaft; ~~and~~

a first liquid discharge mechanism for discharging a liquid in said first line to a drain without supplying the liquid to the substrate; and

a second liquid discharge mechanism for discharging a liquid in said second line to a drain without supplying the liquid to the substrate.

~~a purge gas supply line for supplying a purge gas to a gap between said rotatable shaft and said nozzle structure.~~

#### **4-7 (canceled)**

**8 (currently amended)**      The substrate processing apparatus as recited in claim 1, further comprising a scatter prevention cup disposed outside of a circumference of said substrate holding mechanism so as to encompasse ~~over~~ said substrate holding mechanism, said scatter prevention cup being movable in a vertical direction.

**9 (currently amended)**      A substrate processing method comprising:

holding a substrate withby a substrate holding mechanism withunder a holding force which is ~~produced~~ due to a centrifugal force caused by rotation of the substrate holding mechanism by a substrate rotation mechanism, thereby rotating the substrate;

~~rotating the substrate holding mechanism by a substrate rotation mechanism to rotate the substrate;~~

~~changing a rotational speed of the substrate holding mechanism so as to change the holding force under which the substrate is held by the substrate holding mechanism; and~~

supplying a treatment liquid to a desired portion of the rotating substrate to process the substrate while said changing a rotational speed of the substrate holding mechanism; and-

increasing or decreasing a rotational speed of the substrate holding mechanism so as to cause rotational slipping of the substrate relative to the substrate holding mechanism.

**10 (canceled)**

**11 (currently amended)** The substrate processing method as recited in claim 9, further comprising~~wherein said changing a rotational speed of the substrate holding mechanism comprises:~~ stopping said supplying at~~the~~ substrate treatment liquid simultaneously with or after said increasing or decreasing at~~the~~ rotational speed of the substrate holding mechanism.

**12 (currently amended)** The substrate processing method as recited in claim 9, wherein said increasing or decreasing~~changing~~ a rotational speed of the substrate holding mechanism comprises:

increasing or decreasing~~changing~~ the rotational speed of the substrate holding mechanism from a first rotational speed to a second rotational speed; and then

returning the rotational speed of the substrate holding mechanism from the second rotational speed to the first rotational speed.

**13-20 (canceled)**

**21 (currently amended)** The substrate processing method as recited in claim 9, wherein said supplying ~~at~~ the treatment liquid comprises supplying the treatment liquid to a peripheral portion of the substrate to remove a film formed on the peripheral portion of the substrate.

**22 (original)** The substrate processing method as recited in claim 21, wherein the film to be removed comprises a film containing one of Cu, Co, Co alloy, Ta, Ta-N, W, W-N, Ti, Ti-N, Ni, Ru, P, B, and Mo, or a film having a plurality of layers each containing one of Cu, Co, Co alloy, Ta, Ta-N, W, W-N, Ti, Ti-N, Ni, Ru, P, B, and Mo.

**23-29 (canceled)**

**30 (currently amended)** The substrate processing apparatus as recited in claim 3, further comprising a scatter prevention cup disposed outside of a circumference of said substrate holding mechanism so as to encompass~~over~~ said substrate holding mechanism, said scatter prevention cup being movable in a vertical direction.

**31-35 (canceled)**

**36 (new)** The substrate apparatus as recited in claim 3, further comprising a gas supply nozzle for supplying gas to a space between the substrate and said base member.

**37 (new)** The substrate processing apparatus as recited in claim 3, further comprising a purge gas supply line for supplying a purge gas to a gap between said rotatable shaft and said nozzle structure.